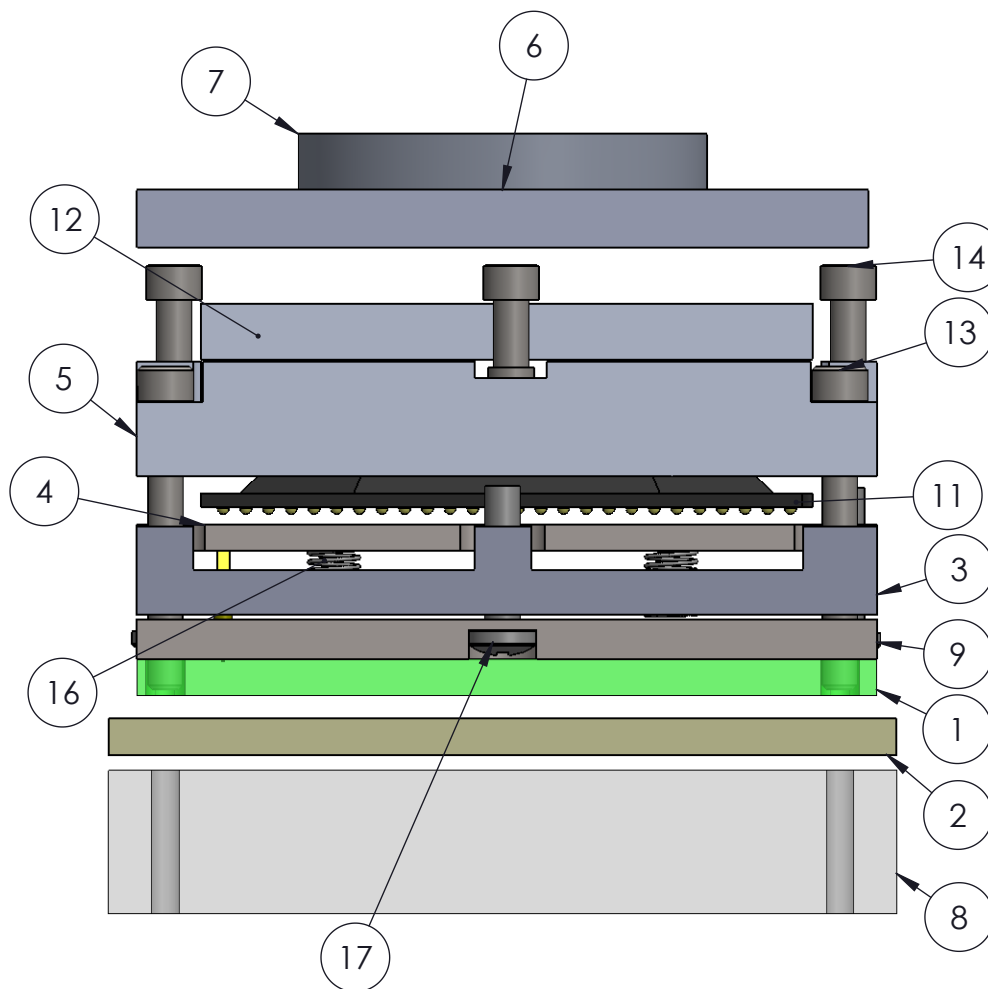


# SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

## Features

- Wide temperature range (-55C to +180C)
- High current capability (up to 8A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time



Description: SBT-BGA Socket 27x27mm, 1mm, 26x26 array

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise.

Materials and specifications are subject to change without notice.

ITEM NO.	Description	Material
1	Test PCB BGA676C	FR4
2	Insulation Plate	FR4/Ultem
3	Middle Guide	PEEK Ceramic filled
4	Floating Guide	PEEK Ceramic filled
5	Socket Base SBT 27x27	7075-T6 Aluminum Alloy
6	Socket Lid	Material <not specified>
7	Compression Screw	7075-T6 Aluminum Alloy
8	Backing Plate 27x27mm	7075-T6 Aluminum Alloy
9	Bottom Guide	PEEK Ceramic filled
10	SBT-BGA pin 1mm pitch	BeCu, Au PLATED OVER Ni
11	BGA with 676pin with 1mm Pitch	
12	Compression PLate	7075-T6 Aluminum Alloy
13	Socket Base Cap Screw	Alloy Steel
14	0-80 Shoulder screw	AISI 321 Annealed Stainless Steel (SS)
15	Dowel pin	Chrome Stainless Steel
16	Floating Guide Spring	Stainless steel
17	Pogo Guide Screw	

## SBT-BGA-6002 Drawing

Ironwood Electronics, Inc.  
Tele: (800) 404-0204  
www.ironwoodelectronics.com

WEIGHT:  
MATERIAL:  
FINISH:

STATUS: Released

DRAWN BY: Vinayak R

File: SBT-BGA-6002 Dwg

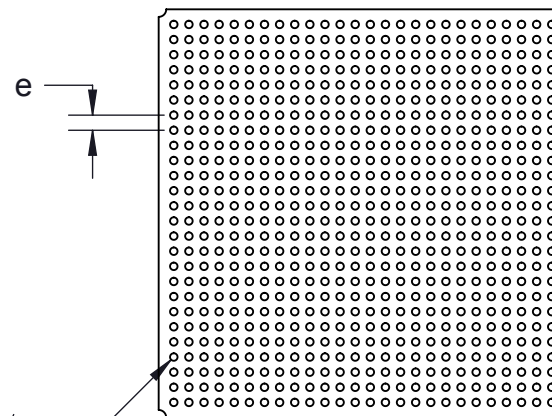
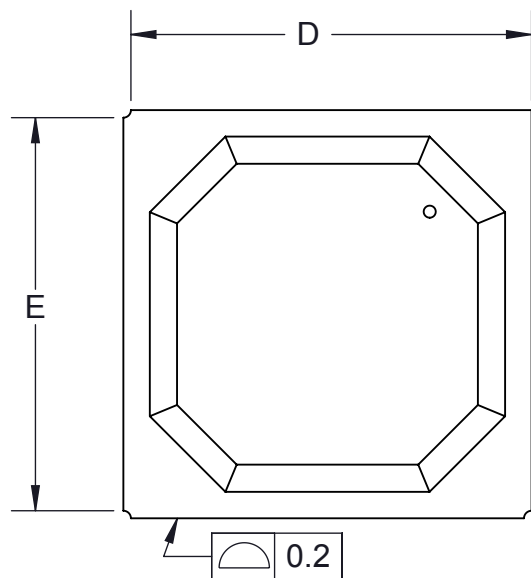
SHEET 1 OF 4

SCALE: 3:1

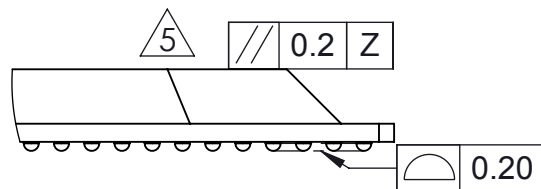
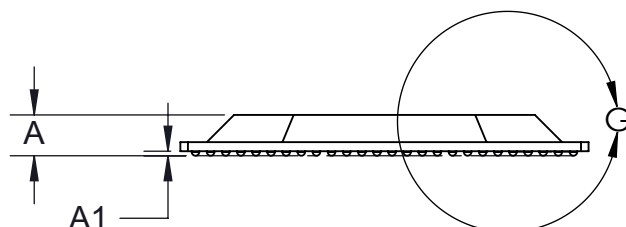
DATE: 11/13/2009

REV. A





$\oplus$	0.25	Z	X	Y
$\oplus$	0.10			



DETAIL G  
SCALE 4 : 1

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	Minimum	Maximum
A		2.5
A1	0.40	0.60
b	0.50	0.70
D	27.0 BSC	
E	27.0 BSC	
e	1.00 BSC	

## Description: BGA676,1mm pitch

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], PCB perimeters  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ], PCB thicknesses  $\pm 0.18\text{mm}$  [ $\pm 0.007"$ ], pitches (from true position)  $\pm 0.08\text{mm}$  [ $\pm 0.003"$ ], all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

26x26 array

## SBT-BGA-6002 Drawing

STATUS: Released

SHEET 3 OF 4

REV. A

Ironwood Electronics, Inc.  
Tele: (800) 404-0204  
www.ironwoodelectronics.com

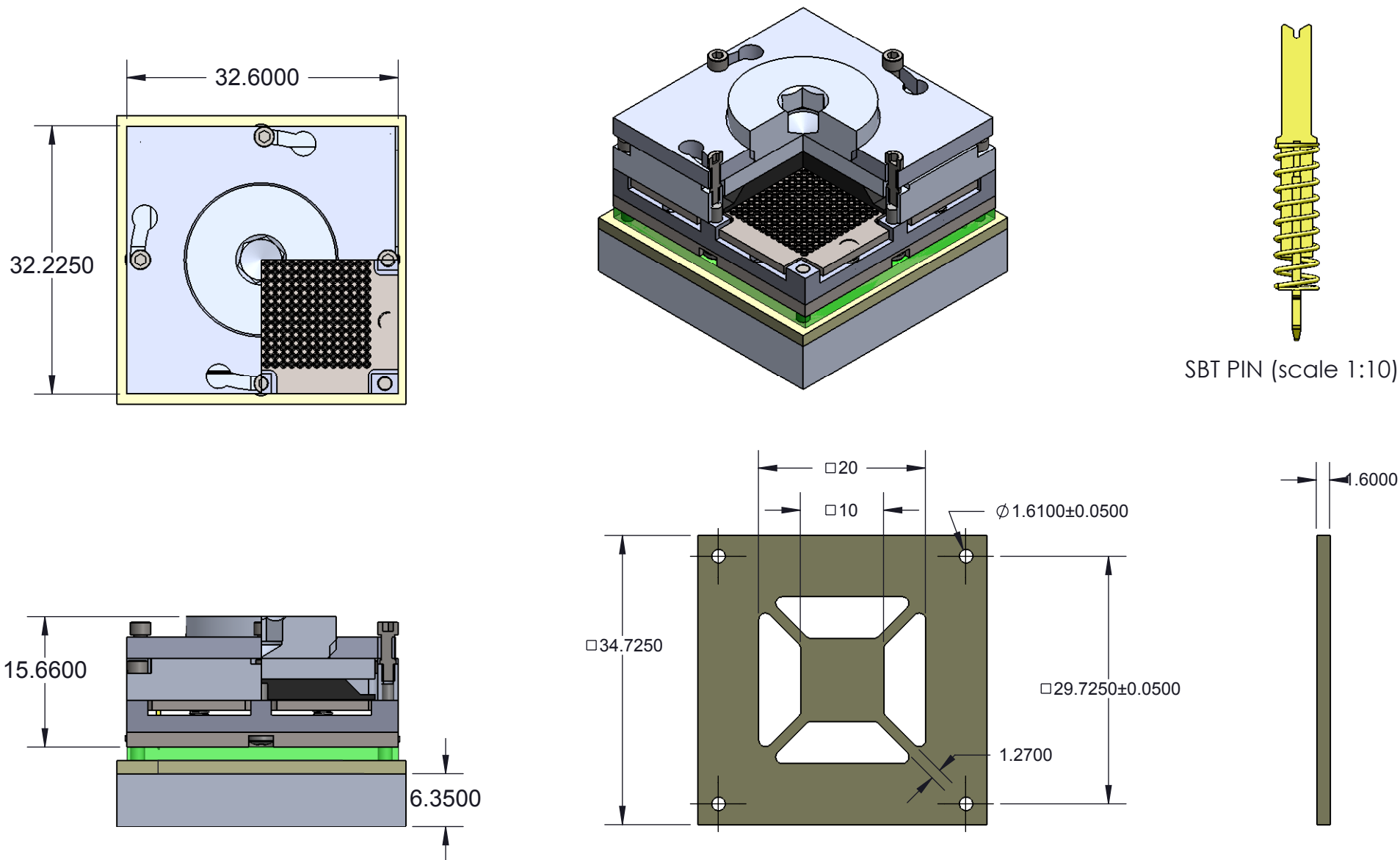
WEIGHT:  
MATERIAL:  
FINISH:

DRAWN BY: Vinayak R

SCALE: 2:1

File: SBT-BGA-6002 Dwg

DATE: 11/13/2009



### Insulation Plate Specification

**Description: Socket Assembly SBT-BGA Socket 27x27mm, 1mm, 26x26 array**

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters  $\pm 0.03\text{mm}$  [ $\pm 0.001"$ ], PCB perimeters  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ], PCB thicknesses  $\pm 0.18\text{mm}$  [ $\pm 0.007"$ ], pitches (from true position)  $\pm 0.08\text{mm}$  [ $\pm 0.003"$ ], all other tolerances  $\pm 0.13\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

### SBT-BGA-6002 Drawing

Ironwood Electronics, Inc.  
Tele: (800) 404-0204  
www.ironwoodelectronics.com

WEIGHT:  
MATERIAL:  
FINISH:

STATUS:Released

DRAWN BY: Vinayak R

File: SBT-BGA-6002 Dwg

SHEET 4 OF 4

SCALE: 3:2

DATE: 11/13/2009

REV. A